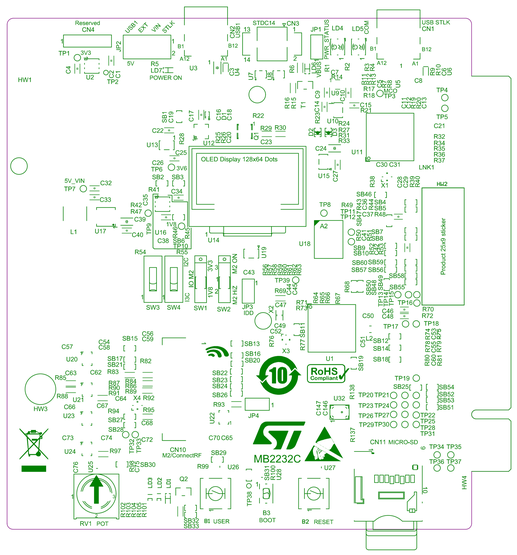
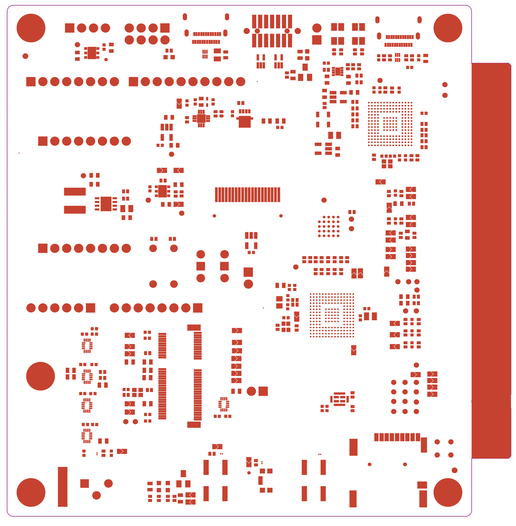
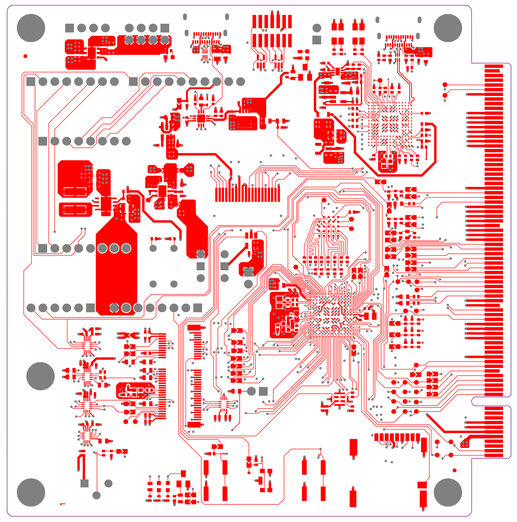


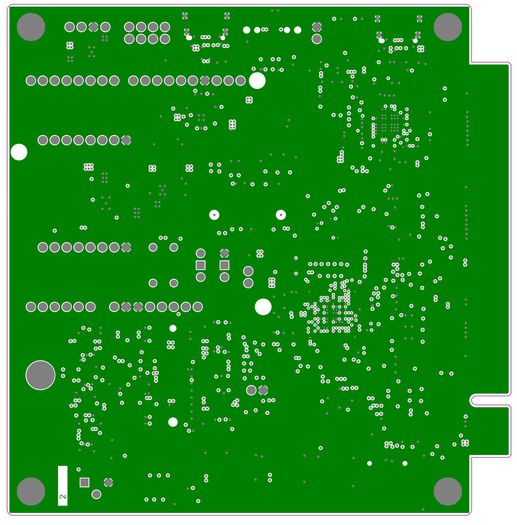
Project: STM32H7P DK board		
Layer: Top Overlay	Gerber: .GTO	
Variant: [No Variations]	Ref: MB2232	
Date: 06-FEB-26	Rev: C	



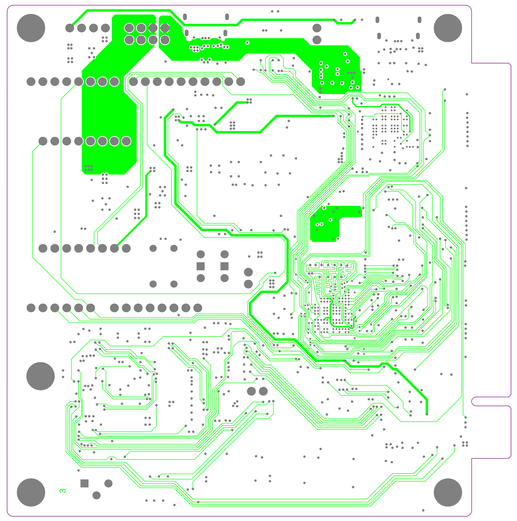
Project: STM32H7P DK board		
Layer: Top Solder	Gerber: .GTS	
Variant: [No Variations]	Ref: MB2232	
Date: 06-FEB-26	Rev: C	



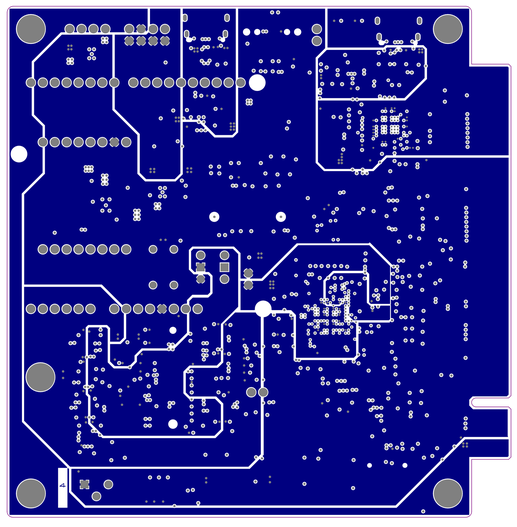
Project: STM32H7P DK board		
Layer: Top Layer	Gerber: .GTL	
Variant: [No Variations]	Ref: MB2232	
Date: 06-FEB-26	Rev: C	



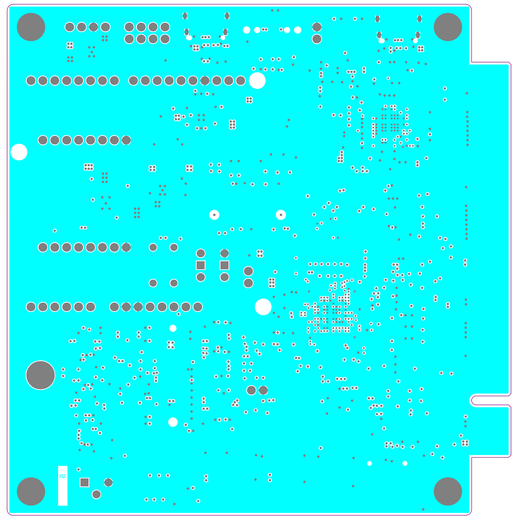
Project: STM32H7P DK board		
Layer: GND	Gerber: .G1	
Variant: [No Variations]	Ref: MB2232	
Date: 06-FEB-26	Rev: C	



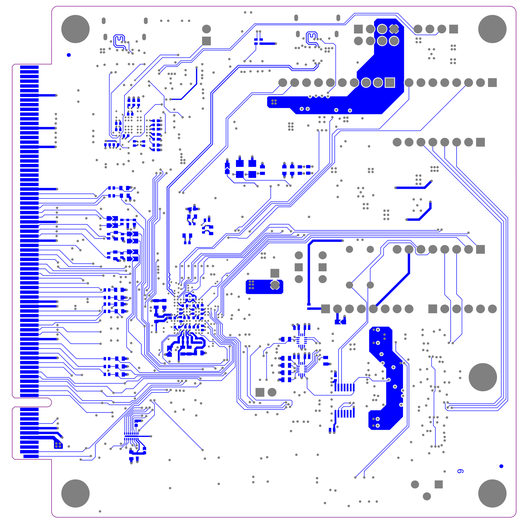
Project: STM32H7P DK board		
Layer: SIG	Gerber: .G2	
Variant: [No Variations]	Ref: MB2232	
Date: 06-FEB-26	Rev: C	



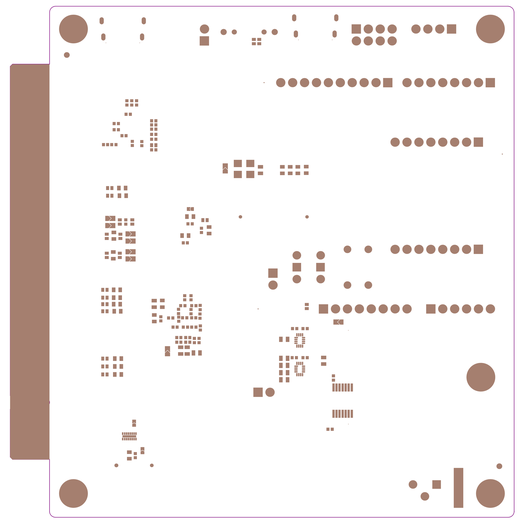
Project: STM32H7P DK board		
Layer: VCC	Gerber:	
Variant: [No Variations]	Ref: MB2232	
Date: 06-FEB-26	Rev: C	



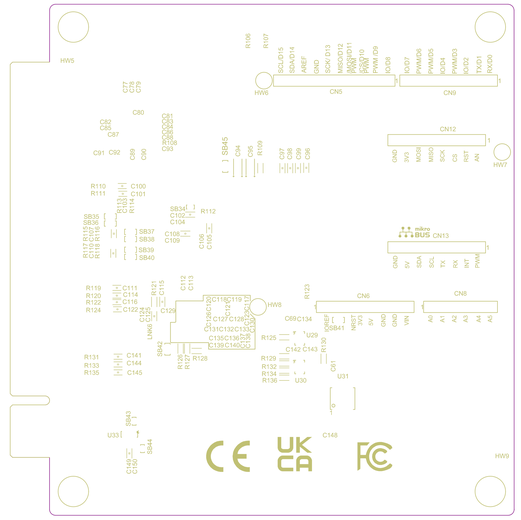
Project: STM32H7P DK board		
Layer: GND	Gerber:	
Variant: [No Variations]	Ref: MB2232	
Date: 06-FEB-26	Rev: C	



Project: STM32H7P DK board		
Layer: Bottom Layer	Gerber:.GBL	
Variant: [No Variations]	Ref: MB2232	
Date: 06-FEB-26	Rev: C	



Project: STM32H7P DK board	
Layer: Bottom Solder	Gerber:.GBS
Variant: [No Variations]	Ref: MB2232
Date: 06-FEB-26	Rev: C

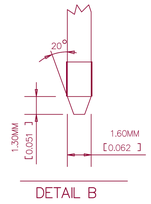


Project: STM32H7P DK board	
Layer: Bottom Overlay	Gerber: .GBO
Variant: [No Variations]	Ref: MB2232
Date: 06-FEB-26	Rev: C

REVISIONS			
REV	DESCRIPTION	DATA	APPROVED
1.0	EDITION ORIGINALE	2008-**-**	***

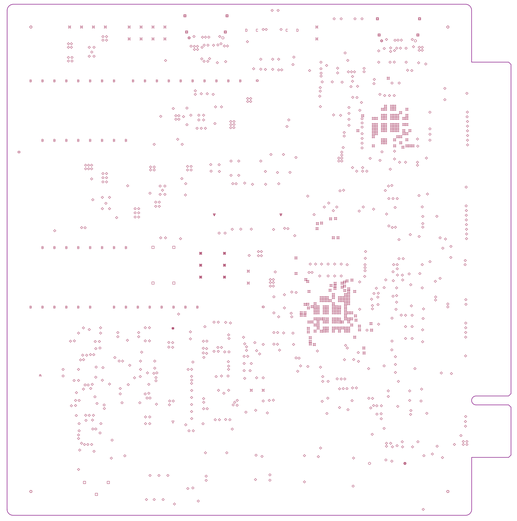
5 IMPEDANCE TABLE

LAYER	TRACE (mil)	SPACEING (mil)	IMPEDANCE (Single end)	IMPEDANCE (Differential)	TOLERANCE
1,3,6	4.0	N/A	55 OHM	N/A	+/-10%
1,6	6.1	8.9	N/A	90 OHM	+/-10%



DETAIL B

Layer	Name	Material	Thickness	Constant	Board Layer Stack	Board Layer Stack	Board Layer Stack	Board Layer Stack
	Top Overlay							
	Top Solder	Solder Resist	0.59mil	3.5				
1	Top Layer		1.30mil					
	Dielectric 1	FR-4	3.90mil	4.2				
2	L2_GND		1.30mil					
	Dielectric 2	FR-4	4.00mil	4.2				
3	L3_SIG		1.30mil					
	Dielectric 3	FR4	38.00mil	4.2				
4	L4_VCC		1.30mil					
	Dielectric4	FR-4	4.00mil	4.2				
5	L5_GND		1.30mil					
	Dielectric5	FR-4	3.90mil	4.2				
6	Bottom Layer		1.30mil					
	Bottom Solder	Solder Resist	0.59mil	3.5				
	Bottom Overlay							



PCB SPECIFICATIONS :

A.	MATERIAL :	FR-4	☐ TG-170	☒ TG-150	☐ TG-140
B.	MATERIAL FAMILY :	N/A			
C.	SOLDERMASK COLOR :	☐ GREEN	☐ WHITE	☐ RED	☐ BLACK ☒ Blue ink PANTONE 2955
D.	SILKSCREEN COLOR :	☒ WHITE	☐ YELLOW	☐ BLACK	☐ Blue ink PANTONE 2955
E.	SURFACE FINISH :	☒ ENIG	☐ IMMERSION SILVER		☐ IMMERSION TIN
		☐ HASL	☐ HASL (PB-FREE)		☐ GOLDEN FINGER
F.	IMPEDANCE CONTROL :	☐ NO	☒ YES (SEE IMPEDANCE TABLE FOR DETAIL INFORMATION)		
G.	THROUGH VIA :	PLUG THE VIAS WHICH ARE COVERED WITH SOLDERMASK ONE OR TWO SIDE.			
		PLUG MATERIAL : ☒ SOLDERMASK ☐ NON-CONDUCTIVE EPOXY.			
H.	STACK-UP :	SEE LAYER STACK-UP SEQUENCE FOR OVERALL THICKNESS.			

PCB : TYPE 3

ASPECT-RATIO, AXE Z :

6:1 to 8:1

MINIMUM PARAMETERS

DEFAULT

TRACKS : 0.127mm

Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Pad Shape	Template	Description	Hole Tolerance (+)	Hole Tolerance (-)	Hole Length	Routed Path Length
	1	27.56mil (0.70mm)	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c0hn70m75				-	-
	1	45.28mil (1.15mm)	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c0hn115m5				-	-
	1	64.96mil (1.65mm)	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c0hn165m5				-	-
A	1	163.39mil (4.15mm)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c600h415m605				-	-
	2	25.59mil (0.65mm)	NPTH	Slot	Top Layer - Bottom Layer	Pad	Rounded	c0hn65_95m5				37.40mil (0.95mm)	11.81mil (0.30mm)
	2	31.50mil (0.80mm)	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c50hn80				-	-
C	2	38.19mil (0.97mm)	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c0hn97m102				-	-
D	2	46.85mil (1.19mm)	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c0hn119m124				-	-
	3	25.59mil (0.65mm)	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded	(Mixed)				-	-
	3	125.98mil (3.20mm)	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c0hn320m10				-	-
	4	137.79mil (3.50mm)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c600h350m605				-	-
	6	35.43mil (0.90mm)	PTH	Round	Top Layer - Bottom Layer	Pad	(Mixed)	(Mixed)				-	-
	7	31.50mil (0.80mm)	PTH	Round	Top Layer - Bottom Layer	Pad	(Mixed)	(Mixed)				-	-
	8	19.69mil (0.50mm)	PTH	Slot	Top Layer - Bottom Layer	Pad	Rounded	r140_80h50_110r100m145_85				43.31mil (1.10mm)	23.62mil (0.60mm)
	18	39.37mil (1.00mm)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	(Mixed)				-	-
B	48	43.31mil (1.10mm)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	(Mixed)				-	-
	213	8.00mil (0.20mm)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded	v41h20m0mx0				-	-
	770	10.00mil (0.25mm)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded	v51h25m0mx0				-	-
	1092 Total												

Slot definitions : Routed Path Length = Calculated from tool start centre position to tool end centre position.
Hole Length = Routed Path Length + Tool Size = Slot length as defined in the PCB layout

Project: STM32H7P DK board	
Layer: Drill Drawing	Gerber: .DRL
Variant: [No Variations]	Ref: MB2232
Date: 06-FEB-26	Rev: C

UNLESS OTHERWISE SPECIFIED	SIGNATURES	DATA
DIMENSIONS ARE IN INCHES	DRAWN	YY-MM-DD
TOLERANCES ON;	CHECKED	YY-MM-DD
2 PL DECIMALS +	ENGGRG	YY-MM-DD
3 PL DECIMALS +	ISSUED	
ANGLES +		
FRACTIONS +		

LOGO	COMPANY NAME	
TITLE	PROJECT NAME *	
SIZE B	DWG NO *******	REV **
SCALE 1:1		SHEET 1 OF 1